

ABSTRACT

A multi-chip package combining wire-bonding and flip-chip configuration includes a plurality of chips, a substrate and a molding compound. Chip(s) with wire-bonding type and a flip-chip type electrical device are mounted on an upper surface of the substrate. A plurality of contact pads of the substrate are formed on the upper surface of the substrate that are not covered by the molding compound, so the flip-chip type electrical device can be electrically connected to these contact pads. The molding compound has recession(s) from a molding tool and seals the chip(s) with wire-bonding type without damaging the contact pads during molding process.